IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: KIM, Sangyum; CHOI, Chang Hee; JO, Cha Jae; KIM, Jeong Ik; WOO, Kyung

Nyung; KI, Joon Seo; MOON, Hong Gi

SERIAL NO.: 10/720,579 ART UNIT: 1753

FILED: November 24, 2003 EXAMINER: Wong, E.

TITLE: METHOD FOR MANUFACTURING VERY LOW ROUGHNESS

ELECTRODEPOSITED COPPER FOIL AND ELECTRODEPOSITED COPPER

FOIL MANUFACTURED THEREBY

AMENDMENT "B"

Director of the U.S. Patent and Trademark Office P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In response to the Final Action of January 3, 2008, having a response being due with a one month extension of time by May, 2008 and concurrent with a Request for Continued Examination, please enter the amendments provided herein and consider the following remarks.

The claims are amended.

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CERTIFICATE OF MAILING UNDER 37 CFR 1.8(a)

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

Sir:

I hereby certify that the attached correspondence comprising:

AMENDMENT "B"

is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to:

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

or by electronic filing on April 24, 2008.

Respectfully submitted,

April 24, 2008	/Andrew W. Chu/
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